

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings of claims in the application:

Claims 1-7 (Canceled).

Claim 8 (Previously Presented): A plasma display panel production process, comprising:

transferring a film forming material layer of a transfer film to a surface of a substrate, thereby obtaining a transferred film forming material layer on said substrate; and

baking the transferred film forming material layer to form an dielectric layer on the substrate;

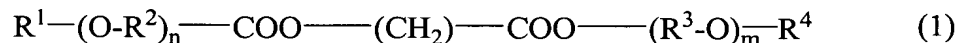
wherein said transfer film comprises a base film and said film forming material layer formed of an inorganic particle-containing composition on the base film;

wherein said inorganic particle-containing composition comprises

(A) an inorganic particle;

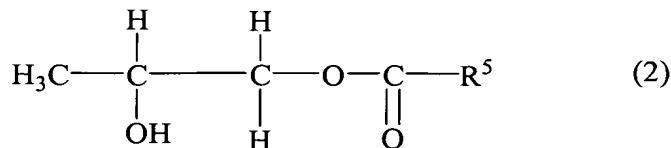
(B) a binder resin; and

(C) at least one plasticizer selected from the group consisting of a compound represented by formula (1):



wherein R^1 and R^4 are the same or different alkyl groups having 1 to 30 carbon atoms or alkenyl groups, R^2 and R^3 are the same or different alkylene groups having 1 to 30 carbon atoms or alkenylene groups, m is an integer of 0 to 5, and n is an integer of 1 to 10,

and compounds represented by the following formula (2):



wherein R⁵ is an alkyl group having 1 to 30 carbon atoms or alkenyl group.

Claim 9 (Previously Presented): A plasma display panel production process,
comprising:

transferring a film forming material layer formed of an inorganic particle-containing composition to a surface of a substrate, thereby obtaining a transferred film forming material layer on said substrate;

forming a resist film on the transferred film forming material layer;

exposing the resist film to form a resist pattern latent image;

developing the resist film to form a resist pattern;

etching the film forming material layer to form a pattern layer corresponding to the resist pattern; and

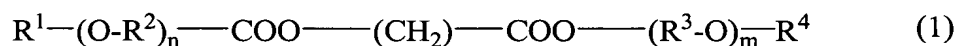
baking the pattern layer to form a constituent element selected from the group consisting of a barrier, an electrode, a resistor, a dielectric layer, phosphor, a color filter and a black matrix;

wherein said inorganic particle-containing composition comprises

(A) an inorganic particle;

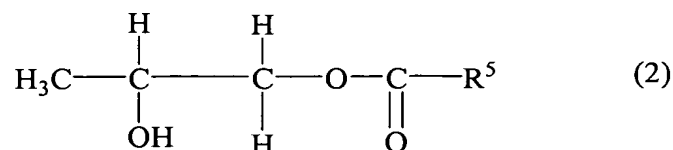
(B) a binder resin; and

(C) at least one plasticizer selected from the group consisting of a compound represented by formula (1):



wherein R¹ and R⁴ are the same or different alkyl groups having 1 to 30 carbon atoms or alkenyl groups, R² and R³ are the same or different alkylene groups having 1 to 30 carbon atoms or alkenylene groups, m is an integer of 0 to 5, and n is an integer of 1 to 10,

and compounds represented by the following formula (2):



wherein R⁵ is an alkyl group having 1 to 30 carbon atoms or alkenyl group.

Claim 10 (Previously Presented): A plasma display panel production process, comprising:

transferring a film forming material layer formed of inorganic particle-containing composition to a surface of a substrate;

forming a resist film on the transferred film forming material layer;

exposing the resist film to form a resist pattern latent image;

developing the resist film to form a resist pattern;

etching the film forming material layer to form a pattern layer corresponding to the resist pattern; and

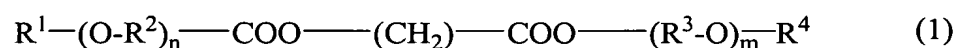
baking the pattern layer to form electrodes;

wherein said inorganic particle-containing composition comprises

(A) an inorganic particle;

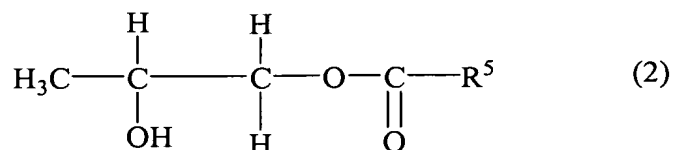
(B) a binder resin; and

(C) at least one plasticizer selected from the group consisting of a compound represented by formula (1):



wherein R¹ and R⁴ are the same or different alkyl groups having 1 to 30 carbon atoms or alkenyl groups, R² and R³ are the same or different alkylene groups having 1 to 30 carbon atoms or alkenylene groups, m is an integer of 0 to 5, and n is an integer of 1 to 10,

and compounds represented by the following formula (2):



wherein R⁵ is an alkyl group having 1 to 30 carbon atoms or alkenyl group;

wherein the inorganic particle (A) is at least one electrically co-aductive particle pa selected from the group consisting of Ag, Au, Al, Ni, Ag-Pd alloy, Cu and Cr.

Claim 11 (Currently Amended): A plasma display panel production process, comprising:

forming a laminate film consisting of a resist film and a film forming material layer ~~formed of comprising~~ an inorganic particle-containing composition on a base film ~~in the order named~~, said resist film being formed on said base film and said film forming material layer being formed on said resist film;

transferring the laminate film formed on the base film to the surface of a substrate;
exposing the resist film constituting the laminate film to form a resist pattern latent image;

developing the resist film to form a resist pattern;

etching the film forming material layer to form a pattern layer corresponding to the resist pattern; and

baking the pattern layer to form a constituent element selected from the group consisting of a barrier, electrode, resistor, dielectric layer, phosphor, color filter and black matrix;

wherein said inorganic particle-containing composition comprises

(A) an inorganic particle;

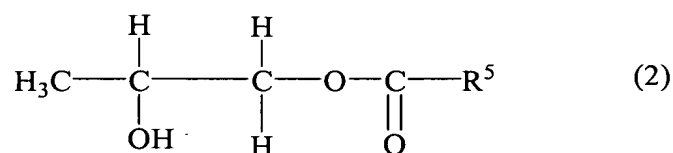
(B) a binder resin; and

(C) at least one plasticizer selected from the group consisting of a compound represented by formula (1):



wherein R^1 and R^4 are the same or different alkyl groups having 1 to 30 carbon atoms or alkenyl groups, R^2 and R^3 are the same or different alkylene groups having 1 to 30 carbon atoms or alkenylene groups, m is an integer of 0 to 5, and n is an integer of 1 to 10,

and compounds represented by the following formula (2):



wherein R^5 is an alkyl group having 1 to 30 carbon atoms or alkenyl group.

Claim 12 (Currently Amended): A plasma display panel production process, comprising:

forming a laminate film consisting of a resist film and a film forming material layer ~~formed of comprising~~ comprising an inorganic particle-containing composition on a base film ~~in the order named, said resist film being formed on said base film and said film forming material layer being formed on said resist film;~~

transferring the laminate film formed on the base film to the surface of a substrate;
exposing the resist film constituting the laminate film to form a resist pattern latent image;

developing the resist film to form a resist pattern;

etching the film forming material layer to form a pattern layer corresponding to the resist pattern; and

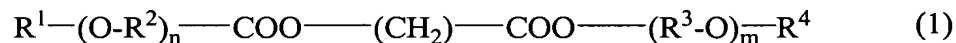
baking the pattern layer to form electrodes;

wherein said inorganic particle-containing composition comprises

(A) an inorganic particle;

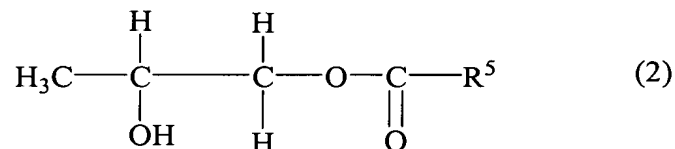
(B) a binder resin; and

(C) at least one plasticizer selected from the group consisting of a compound represented by formula (1):



wherein R^1 and R^4 are the same or different alkyl groups having 1 to 30 carbon atoms or alkenyl groups, R^2 and R^3 are the same or different alkylene groups having 1 to 30 carbon atoms or alkenylene groups, m is an integer of 0 to 5, and n is an integer of 1 to 10,

and compounds represented by the following formula (2):



wherein R^5 is an alkyl group having 1 to 30 carbon atoms or alkenyl group;

wherein the inorganic particle (A) is at least one electrically co-aductive particle selected from the group consisting of Ag, Au, Al, Ni, Ag-Pd alloy, Cu and Cr.

Claim 13 (New) The process according to Claim 11, wherein the laminate film is transferred to said surface of said substrate so that the film forming material layer is in contact with said surface of said substrate.

Claim 14 (New) The process according to Claim 12, wherein the laminate film is transferred to said surface of said substrate so that the film forming material layer is in contact with said surface of said substrate.

Application No.: 09/988,305

Reply to the Office Action dated: October 5, 2004

BASIS FOR THE AMENDMENT

Claims 11 and 12 have been amended as supported at page 32, lines 18-21.

New Claims 13 and 14 have been added as supported at page 28, line 25 to page 29, line 3 of the specification.

No new matter is believed to have been added by entry of this amendment. Entry and favorable reconsideration are respectfully requested.

Upon entry of this amendment Claims 1-14 will now be active in this application.